

WHAT IS CLAIMED IS:

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1. A printed circuit board comprising:
a first wiring line; and
a second wiring line spaced apart from the
first wiring line,
10 the first wiring line having first and
second portions, the first portion having a surface
which faces the second wiring line and is smaller in
area than that of the second portion, so that a
crosstalk noise between the first portion of the
15 first wiring line and the second wiring line can be
reduced.

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2. The printed circuit board as claimed
in claim 1, wherein the second wiring line has third
and fourth portions, the third portion having a
surface which faces the first wiring line and is
25 smaller in area than that of the fourth portion, so
that a crosstalk noise between the third portion of
the second wiring line and the first wiring line can
be reduced.

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3. The printed circuit board as claimed
in claim 1, wherein the first portion of the first
35 wiring line is thinner than the second portion
thereof.

4. The printed circuit board as claimed
in claim 2, wherein the first portion of the first
wiring line is thinner than the second portion
thereof, and the third portion of the second wiring
5 line is thinner than the fourth portion thereof.

10 5. The printed circuit board as claimed
in claim 4, wherein the first portion of the first
wiring line and the third portion of the second
wiring line have an identical height.

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6. The printed circuit board as claimed
in claim 4, wherein the first portion of the first
20 wiring line faces the third portion of the second
wiring line.

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7. The printed circuit board as claimed
in claim 5, wherein the first portion of the first
wiring line faces the third portion of the second
wiring line.

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8. The printed circuit board as claimed
35 in claim 4, wherein:

the first portion of the first wiring line
faces the third portion of the second wiring line;

the second portion of the first wiring line faces the fourth portion of the second wiring line; and

5 a distance between the first and third portions is shorter than that between the second and fourth portions.

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9. The printed circuit board as claimed in claim 5, wherein:

the first portion of the first wiring line faces the third portion of the second wiring line;

15 the second portion of the first wiring line faces the fourth portion of the second wiring line; and

20 a distance between the first and third portions is shorter than that between the second and fourth portions.

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10. The printed circuit board as claimed in claim 1, wherein the first portion of the first wiring line has a triangular cross-sectional shape.

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11. The printed circuit board as claimed in claim 2, wherein the first portion of the first wiring line and the third portion of the second wiring line have a triangular cross-sectional shape.

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12. The printed circuit board as claimed in claim 11, wherein the first portion of the first wiring line and the third portion of the second wiring line have an identical height.

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13. The printed circuit board as claimed in claim 11, wherein the first portion of the first wiring line faces the third portion of the second wiring line.

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14. The printed circuit board as claimed in claim 12, wherein the first portion of the first wiring line faces the third portion of the second wiring line.

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15. The printed circuit board as claimed in claim 1, wherein the first portion of the first wiring line has a trapezoidal cross-sectional shape.

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16. The printed circuit board as claimed in claim 2, wherein the first portion of the first wiring line and the third portion of the second wiring line have a trapezoidal cross-sectional shape.

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17. The printed circuit board as claimed in claim 16, wherein the first portion of the first wiring line and the third portion of the second wiring line have an identical height

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18. The printed circuit board as claimed in claim 16, wherein the first portion of the first wiring line faces the third portion of the second wiring line.

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19. The printed circuit board as claimed in claim 17, wherein the first portion of the first wiring line faces the third portion of the second wiring line.

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20. The printed circuit board as claimed in claim 1, further comprising:

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a third wiring line; and

a fourth wiring line spaced apart from the third wiring line,

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the third wiring line having first and second portions, the first portion having a surface which faces the fourth wiring line and is larger in area than that of the second portion.

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21. The printed circuit board as claimed
in claim 20, wherein the fourth wiring line has
third and fourth portions, the third portion having
a surface which faces the third wiring line and is
5 larger in area than that of the fourth portion.

10 22. The printed circuit board as claimed
in claim 20, wherein the first portion of the third
wiring line is thicker than the second portion
thereof.

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23. The printed circuit board as claimed
in claim 21, wherein the first portion of the third
20 wiring line is thicker than the second portion
thereof, and the third portion of the fourth wiring
line is thicker than the fourth portion thereof.

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24. The printed circuit board as claimed
in claim 23, wherein the first portion of the third
wiring line and the third portion of the fourth
30 wiring line have an identical height.

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25. The printed circuit board as claimed
in claim 23, wherein the first portion of the third
wiring line faces the third portion of the fourth

wiring line.

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26. The printed circuit board as claimed in claim 24, wherein the first portion of the third wiring line faces the third portion of the fourth wiring line.

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27. A printed circuit board comprising:
a first wiring line; and

a second wiring line spaced apart from the first wiring line,

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the first wiring line including a first portion having a surface which faces the second wiring line and is smaller in area than a surface of the second wiring line which faces the first portion of the first wiring line, so that a crosstalk noise between the first portion of the first wiring line and the second wiring line can be reduced.

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28. The printed circuit board as claimed in claim 27, wherein the first portion of the first wiring line is thinner than the second wiring line.

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29. The printed circuit board as claimed in claim 27, further comprising:

a third wiring line; and
a fourth wiring line spaced apart from the
first wiring line,

5 the third wiring line including a first
portion having a surface which faces the fourth
wiring line and is larger in area than a surface of
the fourth wiring line which faces the first portion
of the third wiring line.

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30. The printed circuit board as claimed
in claim 29, wherein the first portion of the third
15 wiring line is thicker than the fourth wiring line.

20 31. A method of forming wiring lines on a
board to form a printed circuit board, comprising
the steps of:

(a) forming the wiring lines of a
predetermined uniform thickness; and

25 (b) etching a first wiring line thereof so
that the first wiring line has a first portion
thinner than a second portion thereof.

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32. The method as claimed in claim 31,
wherein a second wiring line thereof spaced apart
from the first wiring line is etched in the step (b)
35 so as to have a third portion thinner than a fourth
portion thereof.

33. A method of forming wiring lines on a board to form a printed circuit board, comprising the steps of:

5 (a) forming the wiring lines of a predetermined uniform thickness; and

(b) applying a conductive material on a first wiring line thereof so that the first wiring line has a first portion thicker than a second portion thereof.

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34. The method as claimed in claim 33, wherein the conductive material is applied on a second wiring line thereof spaced apart from the first wiring line in the step (b) so that the second wiring line has a third portion thicker than a fourth portion thereof.

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35. A method of forming wiring lines on a board to form a printed circuit board, comprising the steps of:

(a) forming the wiring lines of a predetermined uniform thickness; and

30 (b) grinding a first wiring line thereof so that the first wiring line has a first portion thinner than a second portion thereof.

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36. The method as claimed in claim 35, wherein a second wiring line thereof spaced apart

from the first wiring line is ground in the step (b) so as to have a third portion thinner than a fourth portion thereof.

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